BGA Heat Sink - High Performance maxiFLOW/maxiGRIP-STD





*Image above is for illustration purpose only

ATS Part#: ATS-50170B-C1-R0

Description: 17.00 x 17.00 x 7.50 mm BGA Heat Sink - High Performance maxiFLOW/maxiGRIP-STD

Heat Sink Type: maxiFLOW

Heat Sink Attachment: maxiGRIP

Equivalent Part Number: ATS-50170B-C2-R0 Discontinued

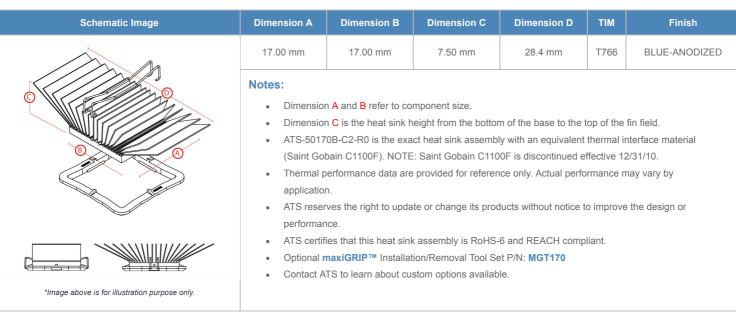
Features & Benefits

- maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB
- Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock and Unpackaged Drop Testing standards
- · Comes preassembled with high performance, phase changing, thermal interface material
- Designed for standard height components from 3 to 4.5mm

Thermal Performance

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	18.2 °C/W	14.8 °C/W	12.8 °C/W	11.4 °C/W	10.4 °C/W	9.7 °C/W	9 °C/W
	Ducted Flow	13.9	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail



For more information, to find a distributor or to place an order, please contact us at 781-769-2800 (North America), sales@qats.com or www.qats.com.



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